Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

2SK2835

Chopper Regulator, DC-DC Converter and Motor Drive Applications

 $\begin{array}{ll} \bullet & \text{Low drain-source ON resistance} & : R_{DS} \ (\text{ON}) = 0.56 \ \Omega \ (\text{typ.}) \\ \bullet & \text{High forward transfer admittance} & : |Y_{fs}| = 4.5 \ S \ (\text{typ.}) \\ \bullet & \text{Low leakage current} & : I_{DSS} = 100 \ \mu\text{A} \ (\text{max}) \ (\text{V}_{DS} = 200 \ \text{V}) \\ \bullet & \text{Enhancement-mode} & : V_{th} = 1.5 \\ \sim 3.5 \ V \ (\text{V}_{DS} = 10 \ \text{V}, I_{D} = 1 \ \text{mA}) \\ \end{array}$

Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	200	V	
Drain-gate voltage (Ro	_{SS} = 20 kΩ)	V_{DGR}	200	V	
Gate-source voltage		V _{GSS}	±20	V	
Drain current	DC (Note 1)	I _D	5	А	
	Pulse (Note 1)	I _{DP}	20	A 	
Drain power dissipation	า	P _D	1.3	W	
Single pulse avalanche	e energy (Note 2)	E _{AS}	65	mJ	
Avalanche current		I _{AR}	5	Α	
Repetitive avalanche e	nergy (Note 3)	E _{AR}	0.13	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature ra	ange	T _{stg}	-55~150	°C	

1.4±0.1 1.05±0.1 1.5±0.15 0.5-0.05 1 2 3 1.SOURCE 2.DRAIN 3.GATE 2-8M1B

Weight: 0.54 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient	R _{th (ch-a)}	96.1	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: V_{DD} = 50 V, T_{ch} = 25°C (initial), L = 4.2 mH, R_G = 25 Ω , I_{AR} = 5 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device.

Please handle with caution.

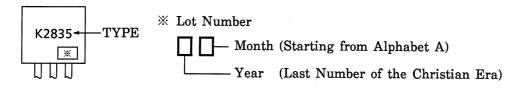
Electrical Characteristics (Ta = 25°C)

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain cut-off cur	rent	I _{DSS}	V _{DS} = 200 V, V _{GS} = 0 V	_	_	100	μΑ
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	200	_	_	V
Gate threshold v	roltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	1.5	_	3.5	V
Drain-source Ol	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 2.5 A	_	0.56	0.8	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 2.5 A	2.0	4.5	_	S
Input capacitano	е	C _{iss}			440	_	pF
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	35	_	
Output capacitance		C _{oss}		_	120	_	
Switching time	Rise time	t _r	V _{GS} 10V I _D =2.5A V _{OUT} R _L =40Ω	_	15	_	- ns
	Turn-on time	t _{on}		_	20	_	
	Fall time	t _f		_	15	_	
	Turn-off time	t _{off}	$V_{DD} = 100V$ Duty $\leq 1\%$, $t_{W} = 10\mu s$	_	60	_	
Total gate charge (gate-source plus gate-drain)		Qg			10	_	
Gate-source charge		Q _{gs}	$V_{DD} \approx 100 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$		6	_	nC
Gate-drain ("miller") Charge		Q _{gd}		_	4	_	

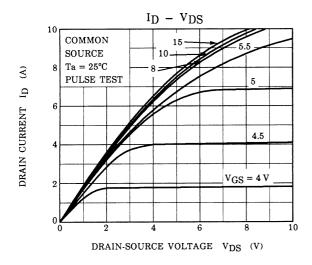
Source-Drain Ratings and Characteristics (Ta = 25°C)

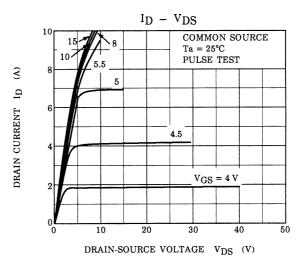
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	-	_	_	5	Α
Pulse drain reverse current (Note 1)	I _{DRP}	-	_	_	20	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 5 A, V _{GS} = 0 V	_	_	-2.0	V
Reverse recovery time	t _{rr}	$I_{DR} = 5 \text{ A}, V_{GS} = 0 \text{ V}, dI_{DR} / dt = 100 \text{ A} / \mu \text{s}$	1	150	_	ns
Reverse recovery charge	Q _{rr}			0.45		μC

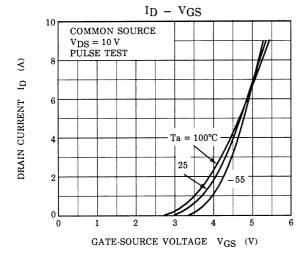
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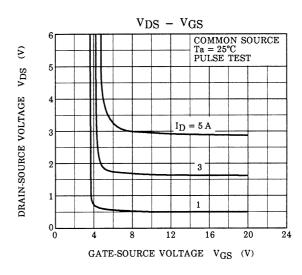


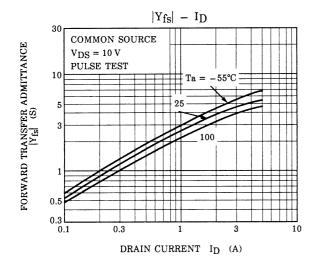
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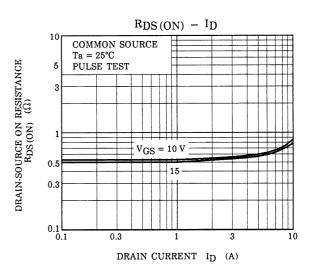




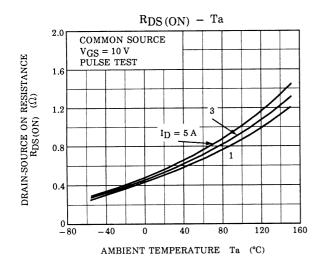


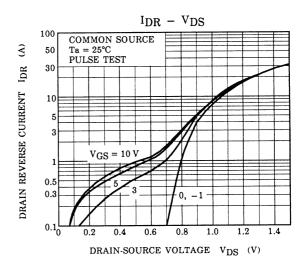


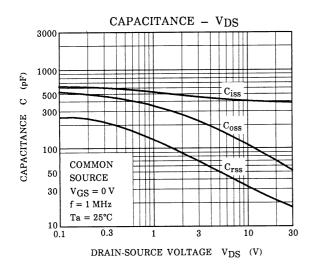


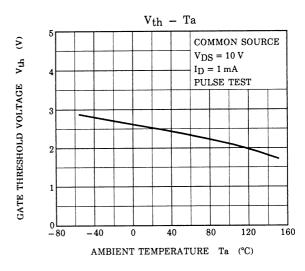


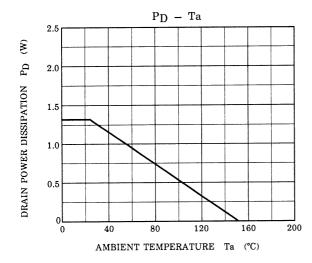
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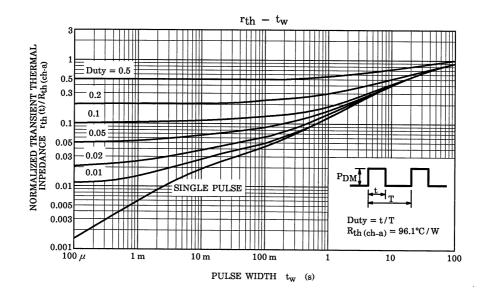


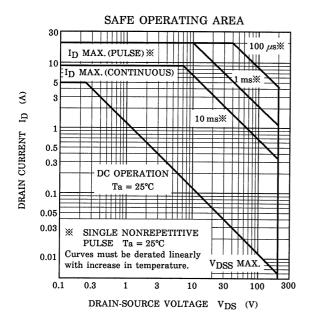


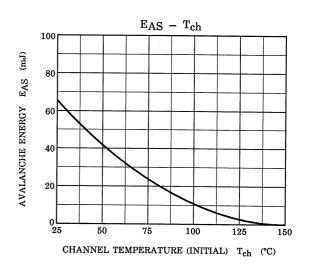


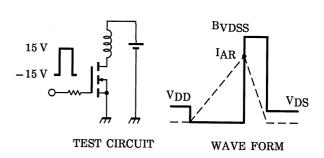


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$$R_G$$
 = 25 Ω
 V_{DD} = 25 V, L = 4.2 mH

$$EAS = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

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